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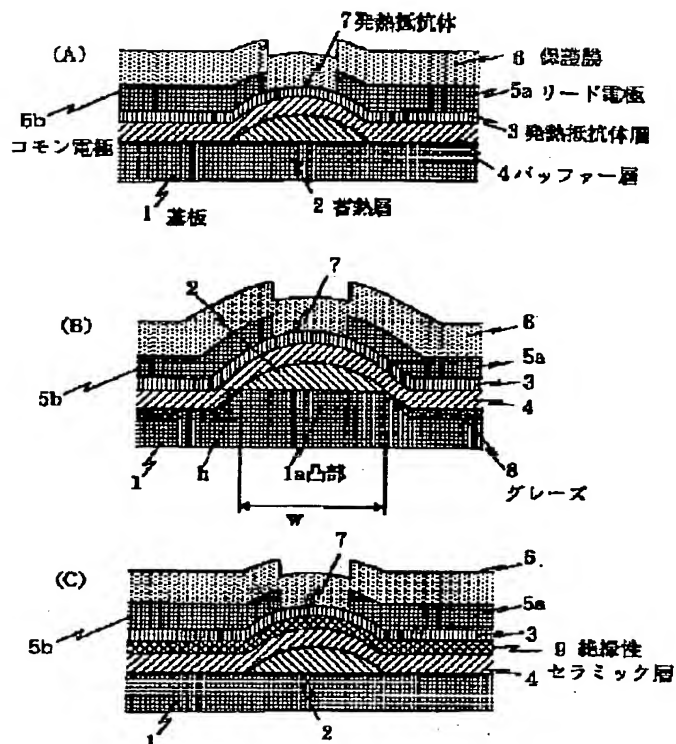
APPLICATION DATE : 22-05-96
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APPLICANT : TDK CORP;

INVENTOR : TOZAWA KAZUO;

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TITLE : THERMAL HEAD



ABSTRACT : **PROBLEM TO BE SOLVED:** To form a thermal head employing polyimide resin in its heat accumulation layer capable of forming a thick, compact buffer layer with low stress, withstanding foreign matter contamination with high efficiency (low consumption of electric power) during the printing period, and having high reliability in its moisture resistance or the like.

SOLUTION: An accumulation layer 2 consisting of polyimide resin is formed on a high heat conductive insulation substrate 1, and a buffer layer 4 is interposed between the accumulation layer 2 and a heat resistance layer 3. The buffer layer 4 is made up of insulation ceramic layer consisting of at least one kind of Si, Al, Mg, Ti, Sr, Y, Mo, Zr, Hf, Ta or W, at least one kind of N or O, and at least one kind of La or Ce.

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